

ABSTRACT OF THE DISCLOSURE

**A WAFER LEVEL SYSTEM FOR PRODUCING BURN-IN/SCREEN, AND
RELIABILITY EVALUATIONS TO BE PERFORMED ON ALL CHIPS
SIMULTANEOUSLY WITHOUT ANY WAFER CONTACTING**

A wafer level system for producing burn-in, voltages screen, and reliability evaluations which are to be performed on all wafers simultaneously without necessitating the probe contacting of any wafer during burn-in/stress. Also provided is a method for implementing the wafer level product burn-in/screen, and semiconductor

5 reliability evaluations on semiconductor chips pursuant to the wafer level system. Pursuant to a preferred aspect all chips of a wafer are stressed simultaneously without having a probe physically contact any chip during the stress procedure. This concept can be applied to burn-in of product wafers, voltage screen of product wafers, and reliability evaluations of various failure mechanisms.

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